

IN THE SPECIFICATION:

Page 1, line 5, insert the following topic headings:

BACKGROUND OF THE INVENTION

FIELD OF THE INVENTION

Page 1, line 8, insert the following topic heading:

THE PRIOR ART

Page 2, line 11, insert the following topic heading:

SUMMARY OF THE INVENTION

Page 9, line 27 to page 10, replace the Table with the following amended Table.

Composition of the dispersion	Concentration as % by weight
Titanium dioxide as finely divided powder	5 to 25
Dioxane	10 to 30
2-methoxy-1-methylethyl acetate	25 to 40
Mixture of dipropylene glycol methyl ether isomers	1 to 15
Disperse-ayd® w33 1)	0.2 to 2
Joncryl® 537 2)	5 to 25
Mixture of tripropylene glycol methyl ether isomers	1 to 5
Dapro ® u99 3)	0.25 to 1
Palladium Copper (II) chloride (metallic salt)	0.05 to 1
Citric Acid (sequestering agent)	0.1 to 1
Ammonia (base)	0.1 to 1
Deionised water	1 to 15

Page 10, lines 11 to 14, replace the paragraph with the following amended paragraph.

The same procedure as in Example 1 is followed. The result is the deposition of a catalytic ~~palladium~~ copper layer, selective or not. In the case of a selective metallisation, the non-irradiated parts are solubilised in water. A metallic overloading by electroplating is then made possible.